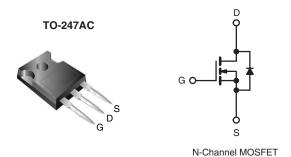


D Series Power MOSFET

PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	450			
R _{DS(on)} max. at 25 °C (Ω)	V _{GS} = 10 V 0.17			
Q _g max. (nC)	88			
Q _{gs} (nC)	12			
Q _{gd} (nC)	23			
Configuration	Single			



FEATURES

 Halogen-free According to IEC 61249-2-21 Definition



HALOGEN FREE

- Optimal Design
 - Low Area Specific On-Resistance
 - Low Input Capacitance (Ciss)
 - Reduced Capacitive Switching Losses
 - High Body Diode Ruggedness
 - Avalanche Energy Rated (UIS)
- Optimal Efficiency and Operation
 - Low Cost
 - Simple Gate Drive Circuitry
 - Low Figure-of-Merit (FOM): Ron x Qg
 - Fast Switching
- Compliant to RoHS Directive 2011/65/EU

APPLICATIONS

- Consumer Electronics
 - Displays (LCD or Plasma TV)
- Lighting
- Industrial
 - Welding
 - Induction Heating
 - Motor Drives
 - Battery Chargers
- SMPS

ORDERING INFORMATION				
Package	TO-247AC			
Lead (Pb)-free	SiHG25N40D-E3			
Lead (Pb)-free and Halogen-free	SiHG25N40D-GE3			

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V _{DS}	400		
Gate-Source Voltage		.,,	± 30	V	
Gate-Source Voltage AC (f > 1 Hz)		V_{GS}	30	İ	
Continuous Drain Current (T _J = 150 °C)	V_{GS} at 10 V $T_{C} = 25 ^{\circ}\text{C}$ $T_{C} = 100 ^{\circ}\text{C}$	1	25	А	
	$T_C = 100 ^{\circ}$ C	- I _D	16		
Pulsed Drain Current ^a	I _{DM}	78			
Linear Derating Factor		2.2	W/°C		
Single Pulse Avalanche Energyb	E _{AS}	556	mJ		
Maximum Power Dissipation	P_{D}	278	W		
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to + 150	°C		
Drain-Source Voltage Slope	T _J = 125 °C	d\//d+	24	V/ns	
Reverse Diode dV/dtd	dV/dt	0.6	V/115		
Soldering Recommendations (Peak Temperature) for 10 s			300°	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 2.3 mH, R_g = 25 Ω , I_{AS} = 17 A.
- c. 1.6 mm from case.
- d. $I_{SD} \le I_D$, starting $T_J = 25$ °C.



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R_{thJA}	-	40	°C/W	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.45	C/VV	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static					•	•	
Drain-Source Breakdown Voltage	V_{DS}	V _{GS}	= 0 V, I _D = 250 μA	400	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I _D = 250 μA	-	0.5	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} :	= V _{GS} , I _D = 250 μA	3	-	5	V
Gate-Source Leakage	I _{GSS}		V _{GS} = ± 30 V	-	-	± 100	nA
7 0		V _{DS} :	= 400 V, V _{GS} = 0 V	-	-	1	μΑ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 320 \	V, V _{GS} = 0 V, T _J = 125 °C	-	-	10	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 13 A	-	0.14	0.17	Ω
Forward Transconductance	9 _{fs}	V_{DS}	= 50 V, I _D = 13 A	-	7.4	-	S
Dynamic				l			
Input Capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$		-	1707	-	
Output Capacitance	C _{oss}	1	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$		177	-	pF
Reverse Transfer Capacitance	C _{rss}		f = 1 MHz	-	19	-	
Total Gate Charge	Qg			-	44	88	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 13 \text{ A}, V_{DS} = 320 \text{ V}$		12	-	nC
Gate-Drain Charge	Q_{gd}				23	-	
Turn-On Delay Time	t _{d(on)}	$V_{DD} = 320 \text{ V}, I_D = 13 \text{ A}, V_{GS} = 10 \text{ V}, R_q = 24.6 \Omega$			21	42	ns
Rise Time	t _r			=.	57	86	
Turn-Off Delay Time	t _{d(off)}			-	40	80	
Fall Time	t _f				37	74	
Gate Input Resistance	R _g	f = 1 MHz, open drain		-	1.8	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET sym showing the	MOSFET symbol showing the		-	24	
Pulsed Diode Forward Current	I _{SM}	integral reverse p - n junction diode		-	-	78	A
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 13 A, V _{GS} = 0 V		-	-	1.2	V
Reverse Recovery Time	t _{rr}	$T_J = 25 ^{\circ}\text{C}, I_F = I_S = 13 \text{A},$ $dI/dt = 100 \text{A/}\mu\text{s}, V_R = 20 \text{V}$		-	353	-	ns
Reverse Recovery Charge	Q _{rr}			_	4.4	-	μC
Reverse Recovery Current	I _{RRM}			_	24	_	A



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

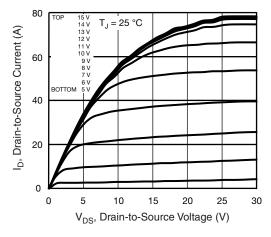


Fig. 1 - Typical Output Characteristics

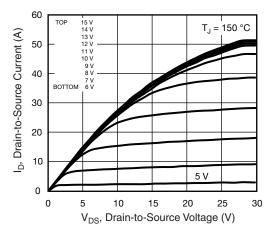


Fig. 2 - Typical Output Characteristics

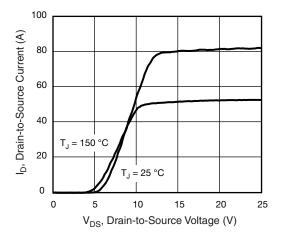


Fig. 3 - Typical Transfer Characteristics

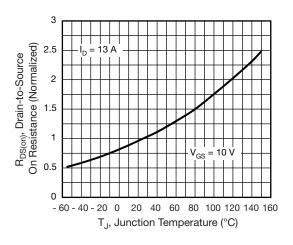


Fig. 4 - Normalized On-Resistance vs. Temperature

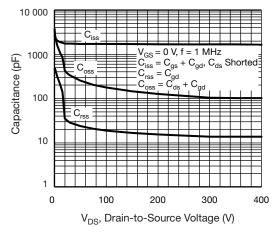


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

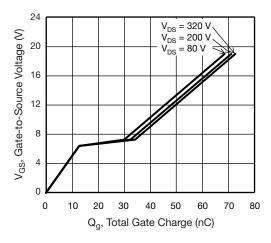


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



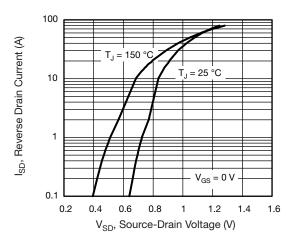


Fig. 7 - Typical Source-Drain Diode Forward Voltage

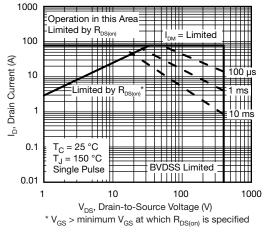


Fig. 8 - Maximum Safe Operating Area

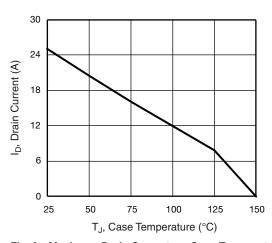


Fig. 9 - Maximum Drain Current vs. Case Temperature

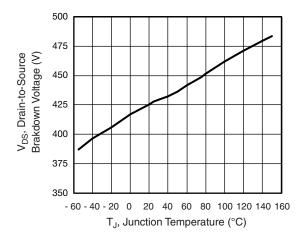


Fig. 10 - Temperature vs. Drain-to-Source Voltage

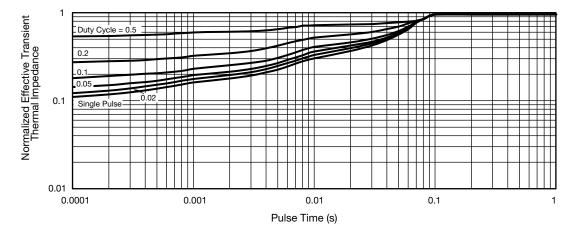


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case



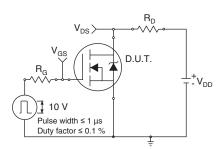


Fig. 12 - Switching Time Test Circuit

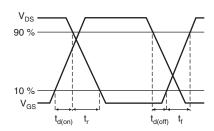


Fig. 13 - Switching Time Waveforms

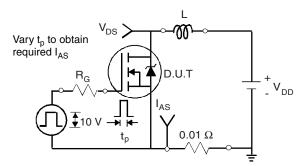


Fig. 14 - Unclamped Inductive Test Circuit

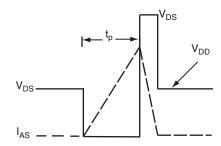


Fig. 15 - Unclamped Inductive Waveforms

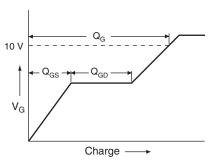


Fig. 16 - Basic Gate Charge Waveform

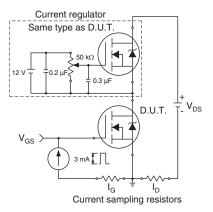
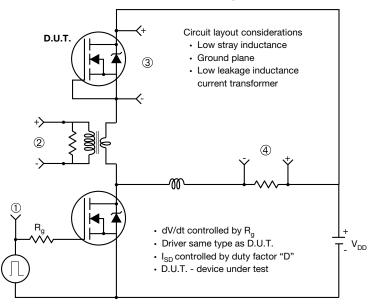


Fig. 17 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



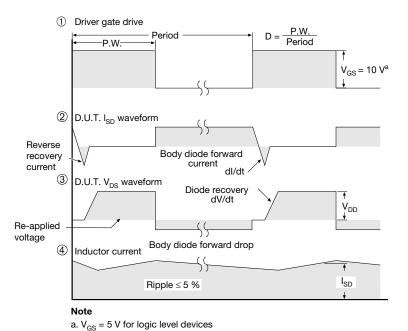
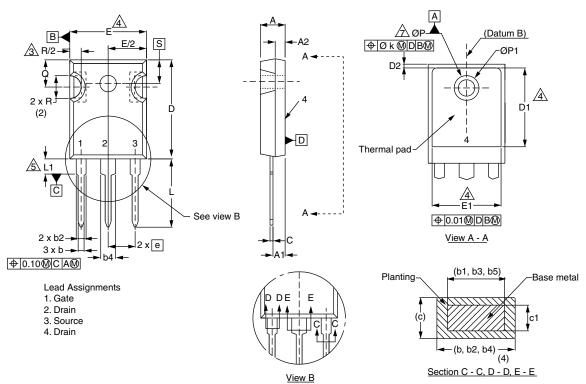


Fig. 18 - For N-Channel

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TO-247AC (High Voltage)



	MILLIMETERS		MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.		
Α	4.58	5.31	0.180	0.209		
A1	2.21	2.59	0.087	0.102		
A2	1.17	2.49	0.046	0.098		
b	0.99	1.40	0.039	0.055		
b1	0.99	1.35	0.039	0.053		
b2	1.53	2.39	0.060	0.094		
b3	1.65	2.37	0.065	0.093		
b4	2.42	3.43	0.095	0.135		
b5	2.59	3.38	0.102	0.133		
С	0.38	0.86	0.015	0.034		
c1	0.38	0.76	0.015	0.030		
D	19.71	20.82	0.776	0.820		
D1	13.08	-	0.515	-		

	MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
D2	0.51	1.30	0.020	0.051
E	15.29	15.87	0.602	0.625
E1	13.72	ı	0.540	ı
е	5.46	BSC	0.215	BSC
Øk	0.2	254	54 0.010	
L	14.20	16.25	0.559	0.640
L1	3.71	4.29	0.146	0.169
N	7.62	BSC	0.300	BSC
ØΡ	3.51	3.66	0.138	0.144
Ø P1	-	7.39	-	0.291
Q	5.31	5.69	0.209	0.224
R	4.52	5.49	0.178	0.216
S	5.51 BSC		0.217 BSC	
0.01200 0.211200				

ECN: X13-0103-Rev. D, 01-Jul-13

DWG: 5971

Notes

- 1. Dimensioning and tolerancing per ASME Y14.5M-1994.
- 2. Contour of slot optional.
- 3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body.
- 4. Thermal pad contour optional with dimensions D1 and E1.
 5. Lead finish uncontrolled in L1.
- 6. Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154").
- 7. Outline conforms to JEDEC outline TO-247 with exception of dimension c.
- 8. Xian and Mingxin actually photo.





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